

List of Publications

International Journal Publication (indexed in Web of Science/SCI)

S. No	Title	Journal & Impact factor
1	<i>Delamination mechanism study of large size waste printed circuit boards by using dimethylacetamide</i> vol. 65, 2017, pp. 139-146	Waste Management (3.829)
2	<i>Liberation of metal clads of waste printed circuit boards by removal of halogenated epoxy resin substrate using dimethylacetamide</i> vol. 60, 2017, pp. 652-659	Waste Management (3.829)
3	<i>Comparative study of printed circuit board recycling by cracking of internal layers using organic solvents- dimethylformamide and dimethylacetamide</i> vol. 142, 2017, pp. 1721-1727	Journal of Cleaner Production (4.959)
4	<i>Dissolution and separation of brominated epoxy resin of waste printed circuit boards by using di-methyl formamide</i> vol. 139, 2016, pp. 586-596	Journal of Cleaner Production (4.959)
5	<i>Effect of milling parameters on the concentration of copper content of hammer-milled waste printed circuit boards</i> Under review	Journal of Sustainable Metallurgy

Conference presentations/proceedings

S.No.	Title	Conference Details
1	<i>A step towards cleaner environment: e-waste recycling. 2015 pp. 21–40</i>	“Advances in Environment Friendly Technology in Mineral Processing and Metal Extraction”, Bhubaneswar
2	<i>Separation of metals from waste printed circuit boards by mechanical / physical techniques. 2014</i>	“National Metallurgist Day-Annual Technical Meeting,” Pune 11-18 Nov’2014
3	<i>Separation of metallic componentes from waste printed circuit boards (PCBs) dissolving brominated epoxy resins (BER) in organic solvents</i>	“International Research Conference on Sustainable Energy, Engineering, Materials and Environment”, 26 th – 28 th July 2017, Northumbria University, Newcastle upon Tyne, UK
4	<i>Recycling of waste printed circuit boards by delamination using different organic solvents and study of its mechanism</i>	“254 th American Chemical Society National Meeting and Exposition”, 20 th – 24 th Aug 2017, Washington DC, USA
5	<i>Enrichment of copper content of waste printed circuit boards by hammer milling and sieve analysis</i>	“Asia Steel, 2018” 6 th -9 th Feb 2018, Bhubaneswar, India
6	<i>Improvement in the leachability of copper of waste printed circuit boards after organic solvent treatment</i>	“Asia Steel, 2018” 6 th -9 th Feb 2018, Bhubaneswar, India